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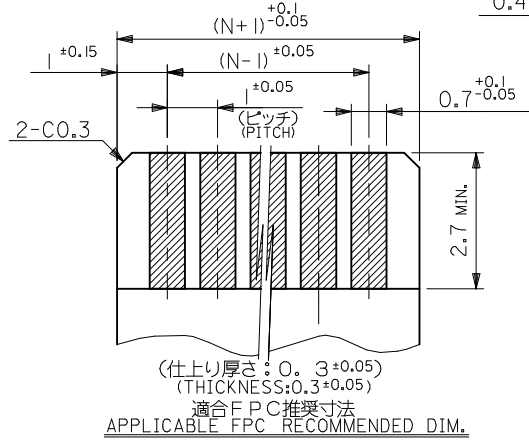
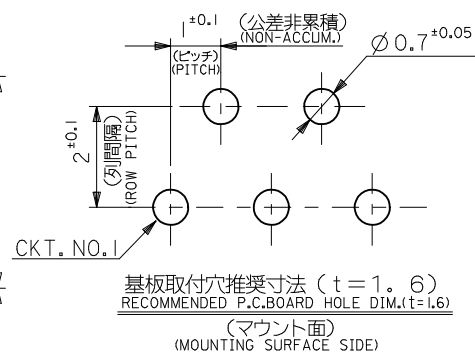
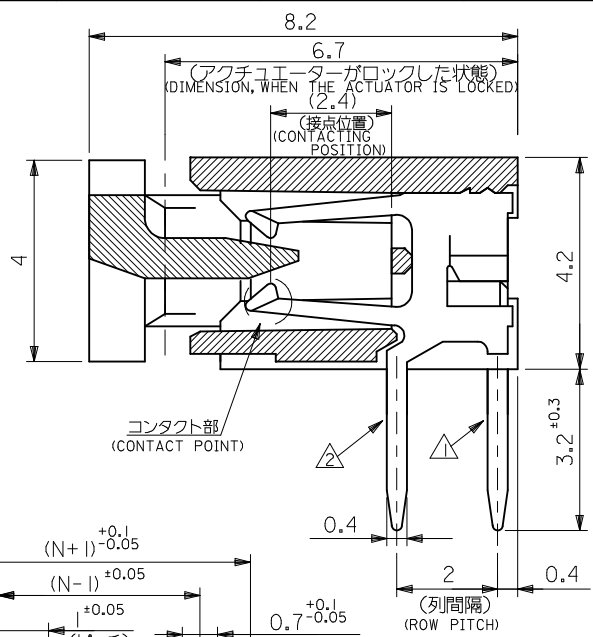
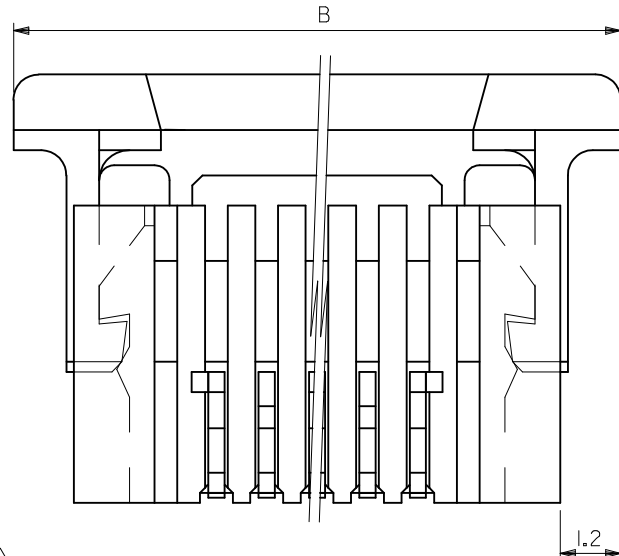
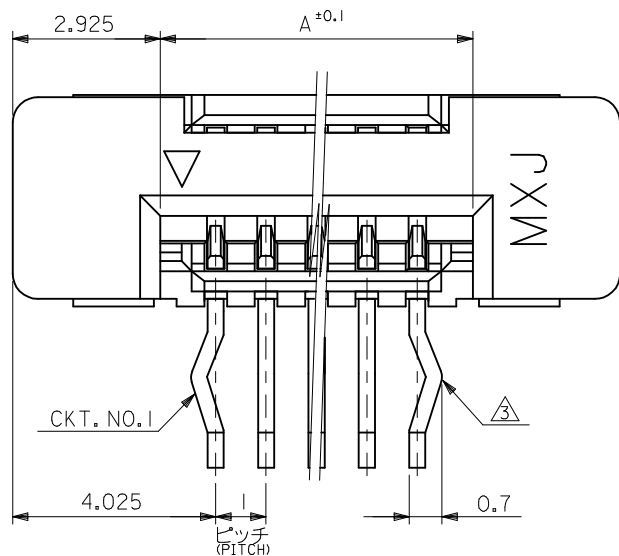
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FPCについて:  
 打抜き方向は導体側から補強板を推奨致します。補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT :  
 THERMOSETTING BONDING AGENT

27.05	21.2	52043-2019	20
25.05	19.2	52043-1819	18
23.05	17.2	52043-1619	16
17.05	11.2	52043-1019	10
16.05	10.2	52043-0919	9
13.05	7.2	52043-0619	6
11.05	5.2	52043-0419	4
B	A	MATERIAL NO.	極数 CKT.

注記:  
 NOTES:  
 ① CKT. NO. 1を基準に偶数番目のソルダータール。  
 EVEN NUMBER SOLDER TAIL.  
 ② CKT. NO. 1を基準に奇数番目のソルダータール。  
 ODD NUMBER SOLDER TAIL.  
 ③ ソルダータールキックは、△のソルダータールの両端部に設ける。  
 KINK TO BE APPLIED FOR THE BOTH END OF ODD NUMBER SOLDER TAIL  
 4. 材 料: ターミナル: リン青銅、ニッケル下地 鍍びスマスマメッキ (t=0.32)  
 MATERIAL: TERMINAL: PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING (t=0.32)  
 ハウジング: 66ナイロン, UL94V-0  
 HOUSING: 66NYLON, UL94V-0  
 アクチュエーター: ポリエステル, UL94V-0  
 ACTUATOR: POLYESTER, UL94V-0  
 5. 本製品は 52043-\*\*10 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52043-\*\*10.

REVISED EC NO: J2016-1317 DRWN: YSHIBATA CHKD: Y0110 APPR: Y0110	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	MODEL NO. 52043-**19
	0.25 UNDER	UNDER	±0.03	DRAWN BY YWADA	DATE 2004/05/19	TITLE 1.0 FPC CONN. Z.I.F R/A	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MSASAO	DATE 2004/05/19		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO. SD-52043-002	SHEET NO. 1 OF 1
10 OVER	30 UNDER	±0.25	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
A	REV	SIZE A3					